



2827

## PATENT APPLICATION

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q63444

Michihiko ICHINOSE

Appln. No.: 09/910,899

Group Art Unit: 2827

Confirmation No.: 3356

Examiner: Luan C. THAI

Filed: July 24, 2001

For: SEMICONDUCTOR DEVICE AND PACKAGING METHOD THEREOF

#### INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents  
Washington, D.C. 20231

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TECHNOLOGY CENTER 2800

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

1. Japanese Unexamined Patent Publication No. 7-22567, published January 24, 1995.
2. Japanese Unexamined Patent Publication No. 9-17910, published January 17, 1997.
3. Japanese Unexamined Patent Publication No. 8-504036, published April 30, 1996.
4. Japanese Unexamined Patent Publication No. 6-53393, published February 25, 1994.
5. Japanese Unexamined Patent Publication No. 7-38240, published February 7, 1995.

One copy of each of the listed documents is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three months from the application's filing date for an application other than a continued prosecution

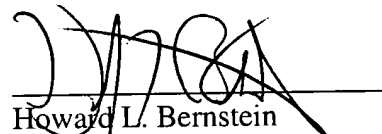
M. ICHINOSE  
Appln. No. 09/910,899  
Information Disclosure Statement

application (CPA) under §1.53(d); (2) Before the mailing date of the first Office Action on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after filing a request for continued examination (RCE) under §1.114, and therefore, no Statement under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

In compliance with the concise explanation requirement under 37 C.F.R. § 1.98(a)(3) for foreign language documents, Applicant encloses herewith a copy of a Japanese Office Action dated January 7, 2003 with an English translation of the pertinent portions thereof which cite such documents and indicate the degree of relevance found by the foreign patent office.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

Respectfully submitted,

  
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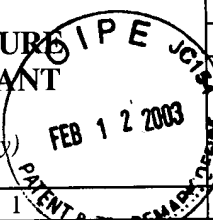
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PATENT TRADEMARK OFFICE

Date: February 12, 2003

Substitute for Form 1449 A & B/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  <i>(use as many sheets as necessary)</i>				<i>Complete if Known</i>	
				Application Number	09/910,899
				Confirmation Number	3356
				Filing Date	July 24, 2001
				First Named Inventor	Michihiko ICHINOSE
				Art Unit	2827
				Examiner Name	Luan C. THAI
Sheet 1 of 1				Attorney Docket Number	Q63444

## U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code <sup>2</sup> (if known)		
		US			
		US			
		US			
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		US			
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## FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)			
		JP	7-22567	A	01-24-1995		No
		JP	9-17910	A	01-17-1997		No
		JP	8-504036	A	04-30-1996		No
		JP	6-53393	A	02-25-1994		No
		JP	7-38240	A	02-07-1995		No

## OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> See Kind Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov), MPEP 901.04 or in the comment box of this document. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to indicate here if English language Translation is attached.

Ref. Q63444

(Regarding Claims 1 through 12) Cited Literature 1 through 5

A semiconductor device subjected to first resin seal packaging having a mounting region and a testing region as stated in Cited Literature 1 through 4, for example, is found to be publicly known.

Moreover, second resin packaging after the mounting of a semiconductor device that has been subjected to first resin seal packaging is found to be customary among members of this industry, as indicated in Reference to Document 5.

#### List of Cited Literature

- 1: Japanese Unexamined Patent Application Publication H7-22567
- 2: Japanese Unexamined Patent Application Publication H9-17910
- 3: Published Japanese Translation of a PCT Application H8-504036
- 4: Japanese Unexamined Patent Application Publication H6-53393
- 5: Japanese Unexamined Patent Application Publication H7-38240